

## Kevin Turner

1234 Wood Lane, Co Cork, Ireland  
Mobile No: +353 12 3456789  
Email: Kevin\_renurt\_m@yahoo.com

---

### Technical Program Management ~ PLM ~ CIM ~ Technical/Manufacturing Operational Systems - IT

OEM • Contract Manufacturing (Electronics)

---

Intend leveraging 28+ years of experience in Electronics Design & Manufacturing, Test Development, Production Management, Vendor Engineering and Procurement including 10 Years in Innovating, Architecting, Developing & Deploying XXX Systems, Yield Prediction, Process Characterization, Optimizing NPI Launches and Product Transfer, Deployment & Implementation.

Versatile, insightful & solution oriented Design and Manufacturing Collaboration SME with experience in engineering and operations within the electronics & technology industry. Proven expertise in ASIC design, product design, fabrication, manufacturing and testing to provide technology solutions for client requirements. Handle development, deployment and rollout of design & manufacturing collaboration systems well. Possess hands-on experience in all facets of Project Management including planning, design, development, commissioning, deployment, monitoring and closing without incidence of time / cost overruns.

Exposure to all facets of product design and development life cycle. Architected a new methodology that can revolutionize product development process within the electronics industry. Transition and centralize essential low-value activities from high to low cost regions for data collection, library generation and development of software solutions. Drive improvements in productivity and process flow while ensuring cost effective operations and resource optimization. Lead Lean & Six Sigma projects. Visionary, rendering sustainable action plans to the Leadership Team to facilitate team and organizational growth. Proactive leader with excellent decision making, negotiation & interpersonal skills. Work well under pressure in a fast paced environment.

#### AREAS OF PROFICIENCY

Budget Management  
XXX & Manufacturing Integration  
Circuit Board Design  
Technology Road Mapping

Business Analysis  
Design Improvements  
Risk Management  
Waste Elimination

International Best Practices  
Recruitment & Development  
Budgeting  
Root Cause Analysis

#### DISTINGUISHED HIGHLIGHTS ACROSS CAREER

##### Company A

- Recognized for outstanding contribution towards the Advanced Technology Group in 2011.
- Determined Methodologies and Tools for quantifying "Process R&D" through "Process Characterization Studies" into "Design Guidelines", resulting in reducing new releases of "Design and Manufacturing Guidelines" from one year to three months.
- Constructed and handled a regional ECAD Library and PCB design team (30 Engineers & Managers) in Malaysia to support XXX Design and XXX team, which provided the company an annualized savings of \$4 million.
- Pioneer in implementing an innovative program "Product Development and Collaboration with Manufacturing", resulting in a cost savings of \$ 50 million year on year.
- Bid and won deals with strategic partner's worth several \$ 10 million.

##### Company B

- Successfully drove a reduction of PCB backlog from 15% of volume to 0.3% during a volume increase of 300% over a 12 month period.

##### Patents

- Received two Patents for "Innovative System and Method Design for IC Chips".

---

## PROFESSIONAL WORK EXPERIENCE

### Senior Director of Engineering Tools and Process, Company A, 2006 to Present

- Assumed responsibility for developing and implementing international standard scalable methodologies, toolsets and best practice process for analysis across more than 24 sites, which not only provided a decisive edge to the firm over its competitors, but also facilitated uniform and repeatable results based on complexity, design technology and manufacturing process.
- Took initiative to study multiple iterations throughout the design cycle and identified, classified & quantified valid issues/defects for streamlining and interfacing the firm's automated XXX process with the client's design process. This not only reduced time-to-market from five days to two days, but also enabled clients reduce product costs, eliminate unnecessary design re-spins and maximize production yields.
- Provided assistance to IT personnel on XXX & AML cleansing and XXX reconciliation between schematic, layout, procurement and manufacturing.
- Supported in integration of XXX Tools & Process with NPI activities to reduce by way of automating the process of NPI setups and product transfers. Implemented measures for improving reliability of new products.
- Handled implementation of eight to ten projects concurrently within defined budget & established parameters at acceptable cost.
- Actively involved in work activities relating to design, XXX and manufacturing related applications such as compiling project charter, ROI calculation, change management and risk mitigation.
- Integrated the XXX analysis process with XXX Product Life Cycle (FPLC), which facilitated placement, training and certification of hundreds of XXX Engineers in several XXX Center of Excellences (COE) across Asia, Western & Eastern Europe and North & South America.
- Expanded the scope of XXX analysis services to include PCB & sheet metal fabrication, PCB & product assembly, tolerance stack-up analysis, fixture stress analysis and XXX & AML Cleansing. Provided assistance in the amalgamation of all these services, resulting in improved customer satisfaction and facilitating service penetration by 30%.
- Established and guided a ECAD Library and PCB design team in Malaysia to assist the firm's Design and XXX team.
- Determined and executed SLA's Service Level Agreements (SLA) and Quality Management System (QMS) for component and library personnel which improved efficiency, expedited delivery and decreased field return.
- Administered the process of establishing and leveraging best practices across different sites. Initiated a system of continuous improvement that facilitated uniformity across multiple sites.

### Director of Engineering Design Services, Company A, 2001 to 2006

- Assumed role of Global Program Manager for managing business for a design and manufacturing collaboration program.
- Liaised with representatives from firm's business partners, Cadence Design Systems Inc. and Hewlett-Packard Co. to initiate an e-commerce company Spin Circuit Inc.
- Teamed with other members of the Steering Committee for implementing Global Best Practices within the firm, with specific emphasis on design, procurement, NPI, manufacturing and testing.
- Handled an international cross functional team of more than 30 Technical Experts, Software Developers, Application Trainers and Technical Content Creators.
- Established a team of Component Engineers in China, Malaysia, and Mexico, along with creating XXX Teams in 34 location across 23 countries.
- Assumed responsibility for understanding customer requirements and providing technical solutions based on the requirements. Coordinated with cross functional teams such Procurement, Design Engineers, Process Engineers, Fabrication Group, Project Manager and XXX Engineers to facilitate product requirements for improving efficiency of design to manufacturing process.
- Assessed software solutions provided by vendors. Examined factors such as IP, integration to Internal System among others for comparing "Buy" versus "In-house Development" Solutions and recommended the most suitable option.
- Created a Project Development team for an integrated XXX Program. Devised and executed several automation tools around component requests, library creation and component data collection.

### Regional Design Center Director, Company A, 2000 to 2001

- Handled operations of the Irish and UK Design Centers. Coordinated design of digitally complex mass storage servers, controllers cards and RF design.
- Actively involved in handling NPI of products developed in the UK & Ireland and facilitating product transfer to other countries such as China, Czech Republic and Mexico.
- Initiated measures for implementing an uniform approach to XXX Analysis and standardized XXX reporting format. Created an awareness on the merits of standardizing and publishing design rules.

**Design Center Manager and Corporate Staff Engineer, Company B, 1998 to 2000**

- Handled a special project concerned with leveraging the Group's state-of-the-art technologies for providing high quality technical solutions to critical client issues.
- Prepared a video presentation for highlighting to investors the merits of vertical integration.
- Coordinated a partnership between Cadence and DII Group to synergize business opportunities in design & manufacturing, thereby facilitating reduction in cost of product development.
- Presented a paper on the theory of XXXX and YYYY testing, to assess the scope for another method for determining product life. The papers were eventually presented to Qualmark and the University of Maryland for assessment.
- Submitted numerous papers on Future Circuits and Future EMS Publications.

**Test /Debug Engineering Manager & Corporate Staff Engineer, Company C, 1995 to 2000**

- Handled Irish testing and debugging & troubleshooting departments. Supervised a team of 30 Engineers and Debug Technicians.
- Took initiative for implementing a product debug tracking system along with a smart card approach to facilitate the quick detection of defects and process faults.
- Rolled out SPC Controls for manufacturing process. Researched new opportunities for defect diagnostics with the assistance of AOI, X-Ray, and thermal analysis.
- Coordinated production process execution for an acquired unit of XXX based in Czech Republic. Implemented measures for ensuring quality of operations in the unit at Czech Republic and for facilitating the IPC 9001 accreditation for the unit.

**Vendor Engineering Manager, Company D, 1992 to 1995**

- Expanded the regional base of vendors for sourcing components & assemblies procured from US, Germany and Japanese suppliers.
- Handled outsourcing of PCB production (both volume high mix and high volume low mix range of products) to Puerto Rico and XXX.

**PCB & Glass Manufacturing and Test Manager, Company E, 1988 to 1992**

- Managed PCB test and administered the operations of glass manufacturing department. Introduced Kan-Ban System & reduced WIP to less than 4 hours of buffer.

**ICT Software Programmer / Test Development Engineer, Company F, 1985 to 1988**

- Actively involved in in-circuit test development and test process management. Interfaced with ICT platform vendors for developing and implementing cluster testing on ICT Platforms.

**Debug Technician, Company F, 1982 to 1985**

- Handled debugging of production & field returns of electronics & electro mechanical products.

---

**TECHNICAL PROFICIENCY**

- Excel, Word, PowerPoint, MS Visio, MS Project, Outlook, Valor Trilogy, Boothroyd & Dewhurst, Cadence Allegro, Concept, Orcad, PE Librarian, Autoplace, Autoroute, SPC and Excel VBA.

**ACADEMIC CREDENTIALS**

- BA (Bachelor of Arts), Irish Management Institute, Ireland, 19XX.
- National Diploma in Electrical Engineering (Credit), Regional Technical College, Dundalk, Ireland, 19XX.
- National Certificate in Electrical Engineering (Credit), Regional Technical College, Sligo, Ireland, 19XX.

---

References furnished upon demand